

1     WHAT IS CLAIMED IS:

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1. A method of mounting a semiconductor device having bumps on a board having pads so that each of said bumps is joined to a corresponding one of said pads, an adhesive to be hardened by heat being provided between said semiconductor device and said board, said method comprising the steps of:

(a) pressing said bumps of said semiconductor device on said pads of said board; and

(b) heating a portion in which each of said bumps and a corresponding one of said pads are in contact with each other, wherein pressure of said bumps against said pads reaches a predetermined value before a temperature of said adhesive to which heat is supplied in step (b) reaches temperature at which said adhesive is hardened.

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2. A method of mounting a semiconductor device having bumps on a board having pads so that each of said bumps is joined to a corresponding one of said pads, an adhesive to be hardened by heat being provided between said semiconductor device and said board, said method comprising the steps of:

(a) causing a head heated at a temperature at which said adhesive is hardened to press said semiconductor device on said board so that each of said bumps is pressed on a corresponding one of said pads, wherein pressure of said bumps against said pads reaches a predetermined value before a temperature of said adhesive to which heat is supplied from said head

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1 reaches temperature at which said adhesive is  
hardened; and

(b) releasing said head from pressing said  
semiconductor device after said adhesive is completely  
5 hardened.

10 3. A method of mounting a semiconductor  
device having bumps on a board having pads so that  
each of said bumps is joined to a corresponding one of  
said pads, an adhesive to be hardened by heat being  
provided between said semiconductor device and said  
15 board, said method comprising the steps of:

(a) providing a member between said  
semiconductor device and said board, said member  
having a thermal characteristic of delaying  
transmission of heat;

20 (b) causing a head heated at a temperature  
at which said adhesive is hardened to press said  
semiconductor device against said board via said  
member so that each of said bumps is pressed against a  
corresponding one of said pads, wherein the  
25 transmission of the heat from said head to said  
adhesive is delayed by said member so that pressure of  
said bumps against said pads reaches a predetermined  
value before a temperature of said adhesive to which  
heat is supplied from said head reaches a temperature  
30 at which said adhesive is hardened; and

(c) releasing said head from pressing said  
semiconductor device after said adhesive is completely  
hardened.

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1           4. The method as claimed in claim 3,  
wherein said member is a sheet, and wherein said step  
(a) has a step of:

5           (a-1) moving said sheet by one step after  
said step (c) so that a new part of said sheet which  
has not yet used is fed into a space between said  
semiconductor device and said board.

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5. The method as claimed in claim 3,  
wherein said member is selected from among a group  
including a polyimide film sheet, a polyester film  
sheet and a silicon film sheet.

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